



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLS820D0EL V33	Issued	18. August 2021
MA#	MA001398414		
Package	PG-SSOP-14-5	Weight*	82.84 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.743	2.10	2.10	21042	21042
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8318	
	non noble metal	copper	7440-50-8	27.978	33.77	34.65	337741	346579
wire	non noble metal	copper	7440-50-8	0.070	0.08	0.08	850	850
encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1207	
	plastics	epoxy resin	-	4.601	5.55		55537	
	inorganic material	silicondioxide	60676-86-0	45.306	54.71	60.38	546919	603663
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11784	11784
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9266	9266
glue	plastics	epoxy resin	-	0.141	0.17		1704	
	noble metal	silver	7440-22-4	0.423	0.51	0.68	5112	6816
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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